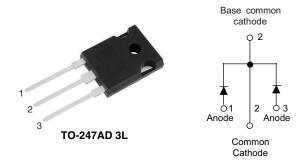


1200 V Power SiC Gen 3 Merged PIN Schottky Diode, 2 x 15 A



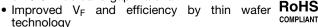
LINKS TO ADDITIONAL RESOURCES



PRIMARY CHARACTERISTICS					
I _F	2 x 15 A				
V _R	1200 V				
V _F at I _F at 25 °C, typ.	1.35 V				
T _J max.	175 °C				
I _R at V _R at 175 °C	6.5 µA				
Q _C (V _R = 800 V)	81 nC				
Package	TO-247AD 3L				
Circuit configuration	Common cathode				

FEATURES

· Majority carrier diode using Schottky technology on SiC wide band gap material



HALOGEN Positive V_F temperature coefficient, for easy FREE

paralleling · Virtually no recovery tail and no switching losses

· Temperature invariant switching behavior

175 °C maximum operating junction temperature

 MPS structure for high ruggedness to forward current surge events

• Meets JESD 201 class 1A whisker test

 Solder bath temperature 275 °C maximum, 10 s per JESD 22-B106

· Material categorization: for definitions of compliance please see www.vishav.com/doc?99912

DESCRIPTION / APPLICATIONS

Wide band gap SiC based 1200 V Schottky diode, designed for high performance and ruggedness.

Optimum choice for high speed hard switching and efficient operation over a wide temperature range, it is also recommended for all applications suffering from Silicon ultrafast recovery behavior.

Typical applications include AC/DC PFC and DC/DC ultra high frequency output rectification in FBPS and LLC converters.

MECHANICAL DATA

Case: TO-247AD 3L

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free, RoHS-compliant

Terminals: matte tin plated leads, solderable per

J-STD-002 and JESD 22-B102

Mounting torque: 10 in-lbs maximum

MAXIMUM RATINGS (T _A = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS			
Peak repetitive reverse voltage	V_{RRM}		1200	V			
Continuous forward surrent per les	I _F ⁽¹⁾	T _C = 147 °C (DC)	15	^			
Continuous forward current, per leg	I _F ⁽²⁾	T _C = 155 °C (DC)	15	Α			
DC blocking voltage, per leg	V_{DC}		1200	V			
Repetitive peak forward current, per leg	I _{FRM}	$T_C = 25$ °C, f = 50 Hz, square wave, DC = 25 %	70				
Nicolar 22 and for a discount and a size	I _{FSM}	$T_C = 25$ °C, $t_p = 10$ ms, half sine wave	110	A			
Non-repetitive peak forward surge current, per leg		$T_C = 110 ^{\circ}\text{C}, t_p = 10 \text{ms}, \text{half sine wave}$	105				
	P _{tot} (1)	T _C = 25 °C	150	W			
		T _C = 110 °C	65	7 VV			
Power dissipation, per leg	D (2)	T _C = 25 °C	214	W			
	P _{tot} (2)	T _C = 110 °C	93				
l ² t value, per leg	∫i ² dt	T _C = 25 °C	61				
	Ji at	T _C = 110 °C	54	- A ² s			
Operating junction and storage temperatures	T _J ⁽³⁾ , T _{Stg}		-55 to +175	°C			

Notes

⁽¹⁾ Based on maximum Rth

⁽²⁾ Based on typical Rth

⁽³⁾ The heat generated must be less than the thermal conductivity from junction-to-ambient: dP_D/dT_J < 1/R_{θJA}



ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS MIN.		TYP.	MAX.	UNITS	
		I _F = 15 A	-	1.35	1.5		
Forward voltage, per leg	V _F	I _F = 15 A, T _J = 150 °C	-	1.73	2.0	V	
		I _F = 15 A, T _J = 175 °C	-	1.85	-		
Reverse leakage current, per leg	I _R	$V_R = V_R$ rated	-	1	75	μΑ	
		V _R = V _R rated, T _J = 150 °C	-	3.5	160		
		V _R = V _R rated, T _J = 175 °C	-	6.5	-		
Total conscitance, per lea	С	V _R = 1 V, f = 1 MHz	-	900	=.		
Total capacitance, per leg		V _R = 800 V, f = 1 MHz	-	56	=.	pF	
Total capacitive charge, per leg	Q _C	V _R = 800 V, f = 1 MHz	-	81	-	nC	

THERMAL - MECHANICAL SPECIFICATIONS (T _A = 25 °C unless otherwise specified)								
PARAMETER SYMBOL TEST CONDITIONS MIN. TYP. MAX. UNITS							UNITS	
They was a variety as a second	per leg	- R _{thJC}		-	0.7	1	°C/W	
Thermal resistance, junction-to-case	per device			-	0.35	0.5	°C/W	
Marking device				3C30CP12L				

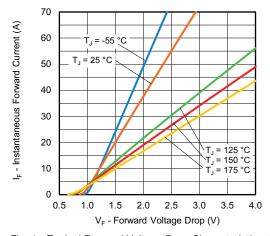


Fig. 1 - Typical Forward Voltage Drop Characteristics, Per Leg

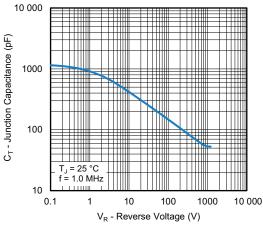


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage, Per Leg

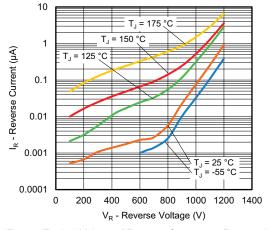


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage, Per Leg

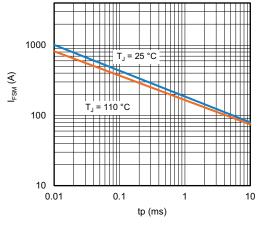


Fig. 4 - Non-Repetitive Peak Forward Surge Current vs. Pulse Duration (Square Wave), Per Leg

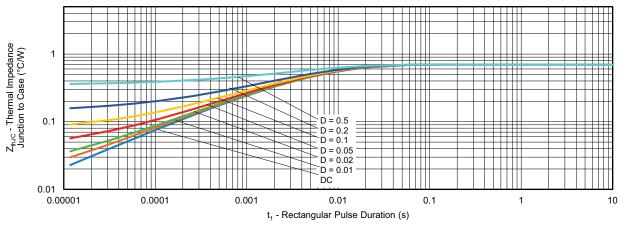


Fig. 5 - Typical Thermal Impedance Z_{thJC} Characteristics, Per Leg

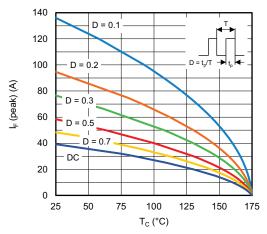


Fig. 6 - Peak Forward Current vs.

Maximum Allowable Case Temperature, Per Leg

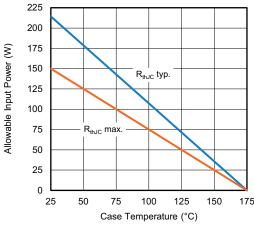


Fig. 7 - Forward Power Loss Characteristics, Per Leg

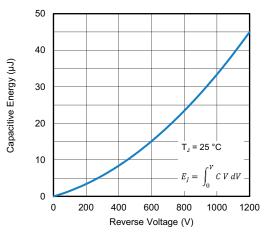


Fig. 8 - Typical Capacitive Energy vs. Reverse Voltage, Per Leg

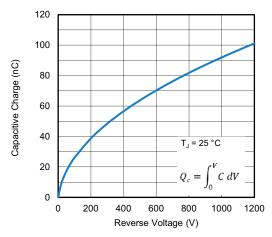
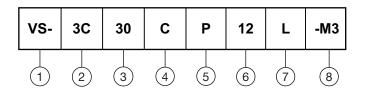


Fig. 9 - Typical Capacitive Charge vs. Reverse Voltage, Per Leg



ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

2 - 3C = SiC diode, Generation 3

3 - Current rating (30 = 30 A)

- C = common cathode

5 - P = package TO-247

6 - Voltage rating: (12 = 1200 V)

7 - L = long lead

8 - Environmental digit:

-M3 = halogen-free, RoHS-compliant, and termination lead (Pb)-free

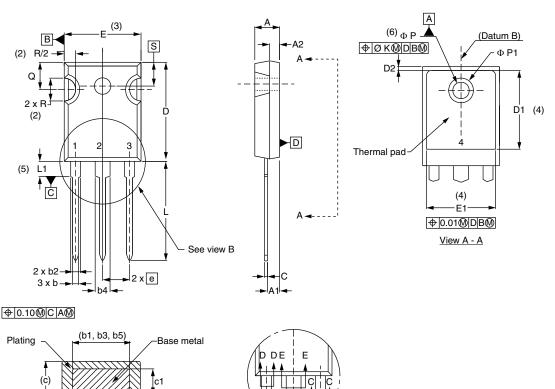
ORDERING INFORMATION		
PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION
VS-3C30CP12L-M3	25 / tube	Antistatic plastic tubes

LINKS TO RELATED DOCUMENTS				
Dimensions	www.vishay.com/doc?95626			
Part marking information	www.vishay.com/doc?95007			



TO-247AD 3L

DIMENSIONS in millimeters and inches



Section C - C, D - D, E - E							
SYMBOL	MILLIN	IETERS	INC	HES	NOTES		
	MIN.	MAX.	MIN.	MAX.	NOTES		
Α	4.65	5.31	0.183	0.209			
A1	2.21	2.59	0.087	0.102			
A2	1.50	2.49	0.059	0.098			
b	0.99	1.40	0.039	0.055			

0.039

0.065

0.065

0.102

0.102

0.015

0.015

0.776

0.515

0.053

0.094

0.092

0.135

0.133

0.035

0.033

0.815

(h h2 h4)

:5	

View B

SYMBOL	IVIILLIIV	ILILING	INCITES		NOTES
	MIN.	MAX.	MIN.	MAX.	NOTES
D2	0.51	1.30	0.020	0.051	
E	15.29	15.87	0.602	0.625	3
E1	13.46	-	0.53	-	
е	5.46 BSC		0.215	BSC	
ØΚ	0.2	254	0.010		
L	19.81	20.32	0.780	0.800	
L1	3.71	4.29	0.146	0.169	
ØΡ	3.56	3.66	0.14	0.144	
Ø P1	-	6.98	-	0.275	
Q	5.31	5.69	0.209	0.224	
R	4.52	5.49	0.178	0.216	
S	5.51 BSC		0.217 BSC		
•	•		•		•

INCHES

MILLIMETERS

Notes

b1

b2

b3

b4

b5

С

с1

D

D1

(1) Dimensioning and tolerancing per ASME Y14.5M-1994

1.35

2.39

2.34

3.43

3.38

0.89

0.84

20.70

- (2) Contour of slot optional
- (3) Dimension D and E do not include mold flash. These dimensions are measured at the outermost extremes of the plastic body

3

- (4) Thermal pad contour optional with dimensions D1 and E1
- (5) Lead finish uncontrolled in L1

0.99

1.65

1.65

2.59

2.59

0.38

0.38

19.71

13.08

- (6) Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")
- (7) Outline conforms to JEDEC® outline TO-247 with exception of dimension A min., D, E min., Q min., S, and note 4



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Vishay

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